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**Title:** CN1381904A: PACKAGE OF LED CHIP AND ITS LIGHT-GATHERING LENS  
**Country:** CN China  
**Kind:** A Unexamined APPLIC. open to Public inspection !  
**Inventor:** ZHIFENG LI; China  
 ZHENGHONG CAI; China  
**Assignee:** YINHE PHOTOELECTRIC CO LTD China  
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**Published / Filed:** 2002-11-27 / 2001-04-18  
**Application Number:** CN2001000115308  
**IPC Code:** H01L 33/00;  
**ECLA Code:** None  
**Priority Number:** 2001-04-18 CN2001000115308  
**Abstract:**



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A LED chip package is composed of a PCB substrate with a conductor layer and an electrode on its one surface, a LED chip on the said conductor layer and connected with the said electrode via a wire, and a light gathering lens of strut shape with internal concave surface and external convex surface corresponding to the position of LED chip and connected to PC substrate.

**Family:**

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<input checked="" type="checkbox"/>	CN1381904A	2002-11-27	2001-04-18	PACKAGE OF LED CHIP AND ITS LIGHT-GATHERING LENS
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**Other Abstract Info:**

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